

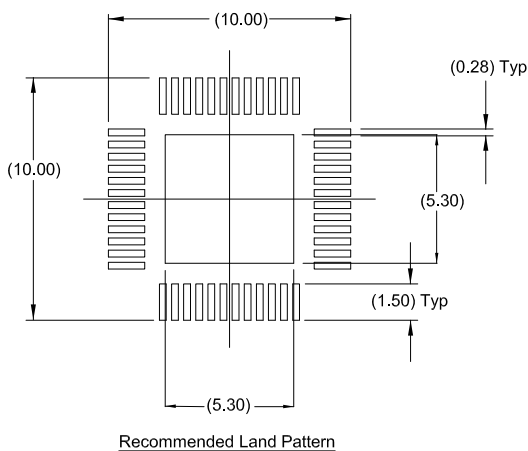
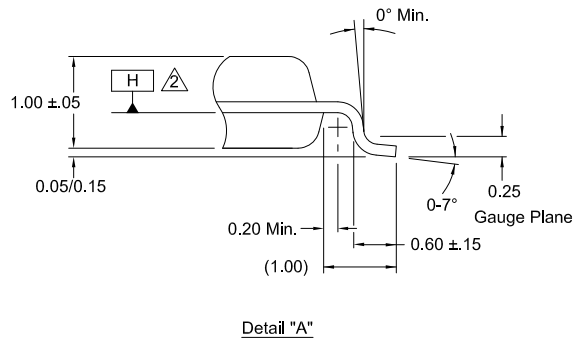
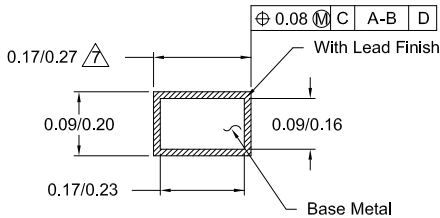
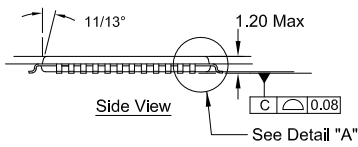
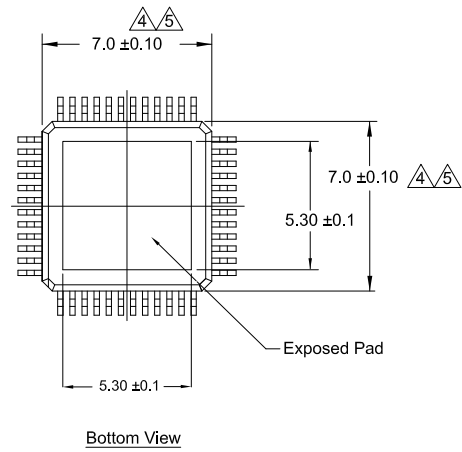
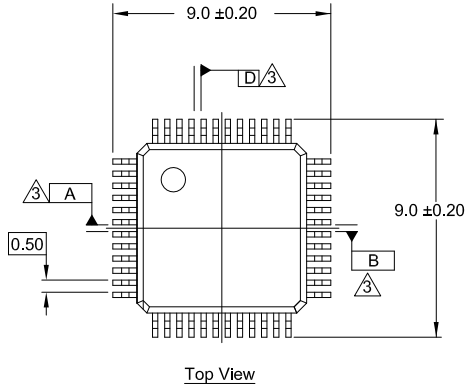
Plastic Packages for Integrated Circuits

Package Outline Drawing

Q48.7x7C

48 Lead Thin Plastic Quad Flatpack Exposed Pad Package (TQFP-EP)

Rev 0, 8/2022



NOTES:

- All dimensioning and tolerancing conform to ANSI Y14.5-1982.
- Datum plane [H] located at mold parting line and coincident with lead, where lead exits plastic body at bottom of parting line.
- Datums [A-B] and [D] to be determined at centerline between leads where leads exit plastic body at datum plane [H].
- Dimensions do not include mold protrusion. Allowable mold protrusion is 0.254 mm.
- These dimensions to be determined at datum plane [H].
- Package top dimensions are smaller than bottom dimensions and top of package does not overhang bottom of package.
- Dimension does not include dambar protrusion. Allowable dambar protrusion is 0.08mm total in excess of the dimension at maximum material condition. Dambar cannot be located on the lower radius or the foot.
- Controlling dimension: millimeter.
- This outline conforms to jecdec publication 95 registration MS-026, variation ABC-HD
- Dimensions in () are for reference only.